



Packet No. 70012200-0065-0005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re U.S. Patent App. of Richards)

Serial No.: 10/040,412)

Art Unit: [not yet assigned]

Filed: January 7, 2002)

Examiner: [not yet assigned]

For: CLEAR, POLYMERIC GEL
COMPOSITION AND METHOD
FOR PRODUCING THE SAME)

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir or Madam:

In accordance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, Applicant submits the following statement consisting of:

- I. A list of patents (and attached Form PTO-1449).
- II. General Remarks.

A copy of each of the following listed documents is enclosed herewith.

I. PATENTS

- 1. U.S. Pat. No. 4,497,663;
- 2. U.S. Pat. No. 4,857,563;
- 3. U.S. Pat. No. 5,780,527;
- 4. U.S. Pat. No. 5,334,691;
- 5. U.S. Pat. No. 4,362,841;
- 6. U.S. Pat. No. 5,663,341;
- 7. U.S. Pat. No. 5,844,047;
- 8. U.S. Pat. No. 5,792,816;

PATENT

RECEIVED
JAN 09 2003
TECH CENTER 1600/2900

RECEIVED
FEB 03 2003
TECH CENTER 1600/2900

9. WIPO Pat. No. WO0178792; and
10. FR Pat. No. 2455068.

II. GENERAL REMARKS

It is respectfully requested that the above-listed patents be given consideration by the Examiner and made of record in the subject patent application. This Information Disclosure Statement is being submitted before the mailing date of a first Office Action on the merits and therefore no fee is required.

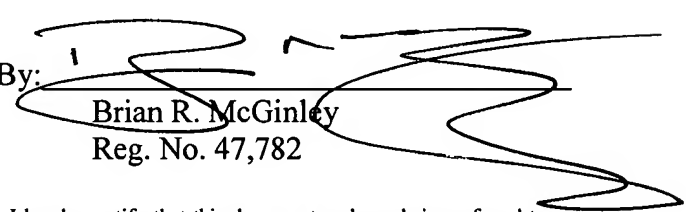
Please acknowledge receipt by returning the enclosed postcard. We kindly request that any questions be directed to the undersigned.

Respectfully submitted,

SONNENSCHN NATH & ROSENTHAL

January 24, 2003

By:


Brian R. McGinley
Reg. No. 47,782

SONNENSCHN NATH & ROSENTHAL
P.O. Box 061080
Wacker Street Station, Sears Tower
Chicago, IL 60606-1080
(816) 460-2400 (phone)
(816) 531-7545 (facsimile)

I hereby certify that this document and any being referred to as attached or enclosed is being deposited with the United States Postal Service as first class mail in an envelope addressed to Assistant Commissioner for Patents, Washington, D.C. 20231, on

01-24-2003

Date


Lea Page